

General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® S series is optimized for its switching characteristics to achieve aggressive EMI standards. It is easy to use for smaller power supply systems to meet the both efficiency and EMI standards.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity



Applications

- LED lighting
- Charger
- Adapter
- Telecom power
- Server power
- Solar/UPS

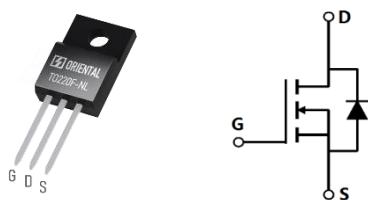
Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	700	V
$I_D, pulse$	60	A
$R_{DS(ON), max} @ V_{GS}=10V$	200	mΩ
Q_g	45.4	nC

Marking Information

Product Name	Package	Marking
OSG65R200FSF_NB	TO220F_NL	OSG65R200FS

Package & Pin Information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	650	V
Gate-source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	20	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		12.5	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	60	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	20	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S,\text{pulse}}$	60	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	34	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	578	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\ldots 480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\ldots 480\text{ V}$, $I_{SD} \leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	3.67	°C/W
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62.5	°C/W

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	650			V	$V_{GS}=0\text{ V}$, $I_D=250\text{ }\mu\text{A}$
		700				$V_{GS}=0\text{ V}$, $I_D=250\text{ }\mu\text{A}$, $T_j=150^\circ\text{C}$
Gate threshold voltage	$V_{GS(\text{th})}$	2.9		3.9	V	$V_{DS}=V_{GS}$, $I_D=250\text{ }\mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		0.15	0.2	Ω	$V_{GS}=10\text{ V}$, $I_D=10\text{ A}$
			0.37			$V_{GS}=10\text{ V}$, $I_D=10\text{ A}$, $T_j=150^\circ\text{C}$
Gate-source leakage current	I_{GS}			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	I_{DS}			1	μA	$V_{DS}=650\text{ V}$, $V_{GS}=0\text{ V}$
Gate resistance	R_G		8.8		Ω	$f=1\text{ MHz}$, Open drain

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		1745		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 kHz
Output capacitance	C _{oss}		102		pF	
Reverse transfer capacitance	C _{rss}		2.6		pF	
Effective output capacitance, energy related	C _{o(er)}		58		pF	V _{GS} = 0V, V _{DS} = 0V-400V
Effective output capacitance, time related	C _{o(tr)}		288		pF	
Turn-on delay time	t _{d(on)}		28.2		ns	V _{GS} =10 V, V _{DS} =400 V, R _G =2 Ω, I _D =10 A
Rise time	t _r		11		ns	
Turn-off delay time	t _{d(off)}		70.8		ns	
Fall time	t _f		7.8		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		45.4		nC	V _{GS} =10 V, V _{DS} =400 V, I _D =4 A
Gate-source charge	Q _{gs}		10.2		nC	
Gate-drain charge	Q _{gd}		12.5		nC	
Gate plateau voltage	V _{plateau}		5.4		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =20 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		320		ns	
Reverse recovery charge	Q _{rr}		4.1		μC	
Peak reverse recovery current	I _{rrm}		23.2		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=100 V, V_{GS}=10 V, L=79.9 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

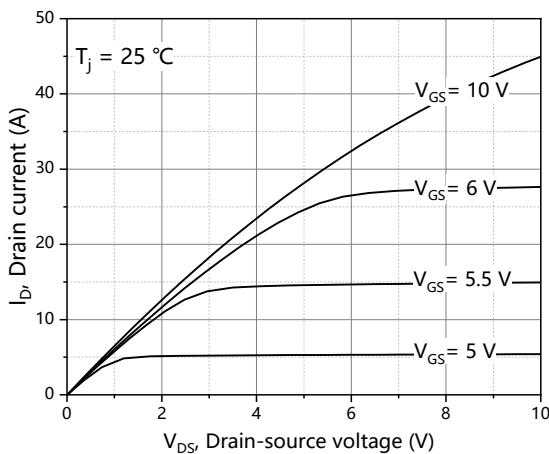


Figure 1. Typ. output characteristics

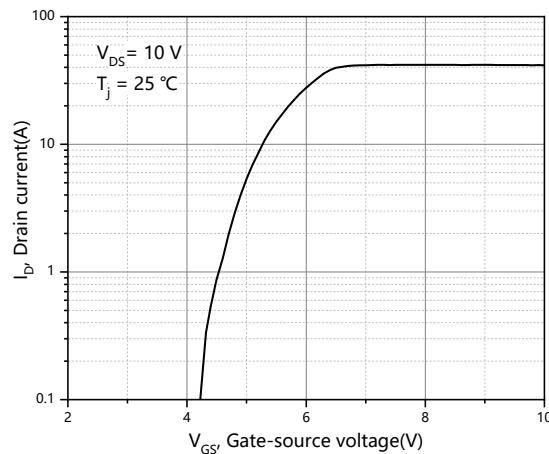


Figure 2. Typ. transfer characteristics

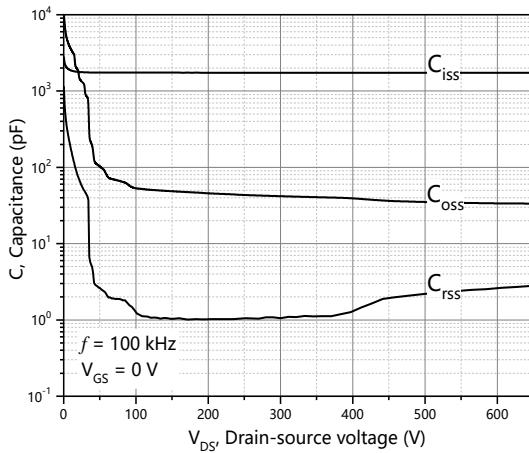


Figure 3. Typ. capacitances

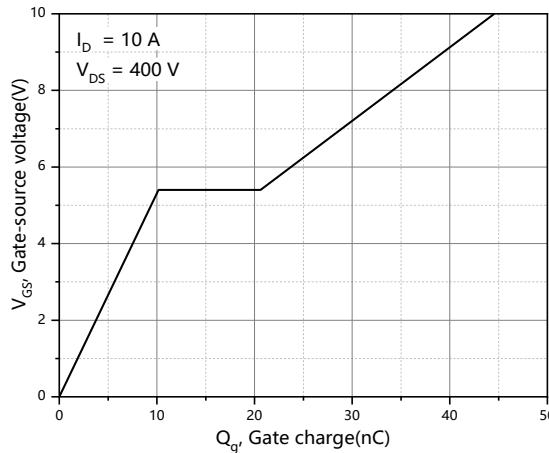


Figure 4. Typ. gate charge

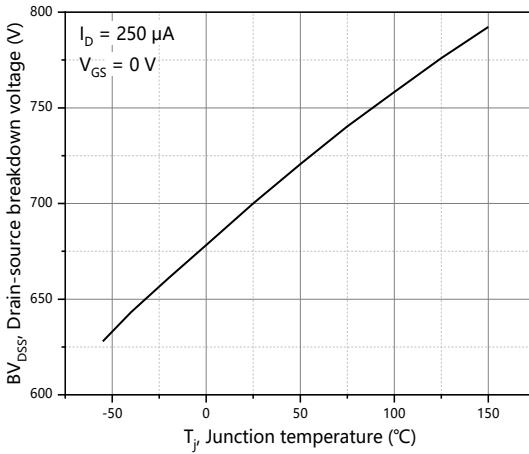


Figure 5. Drain-source breakdown voltage

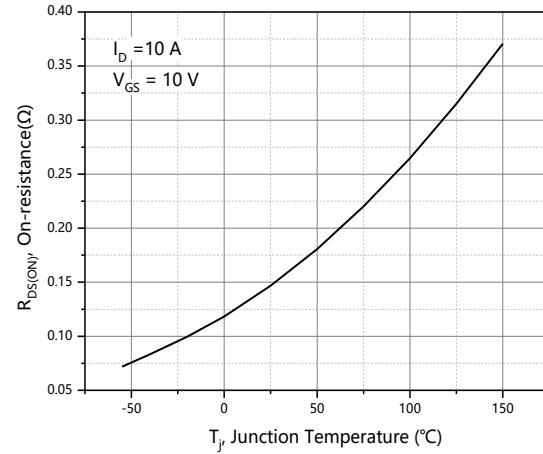
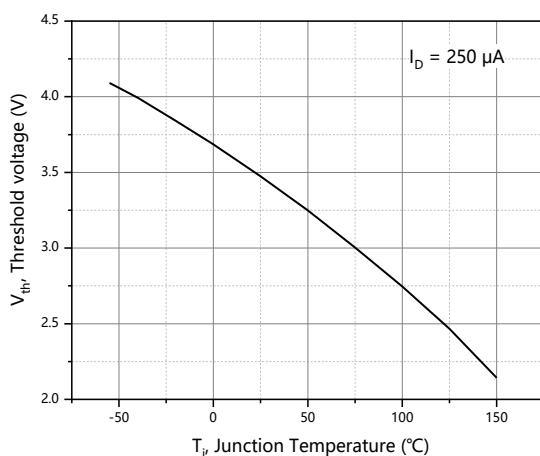
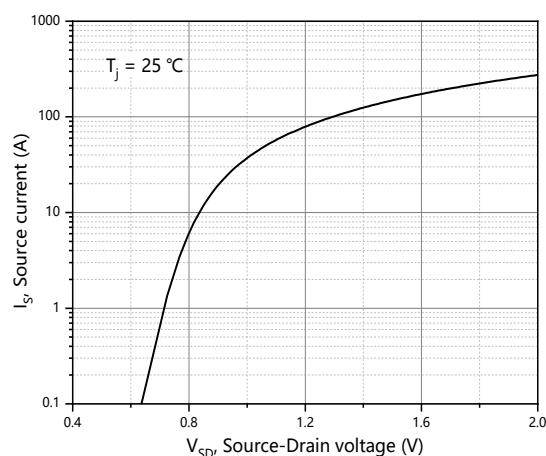
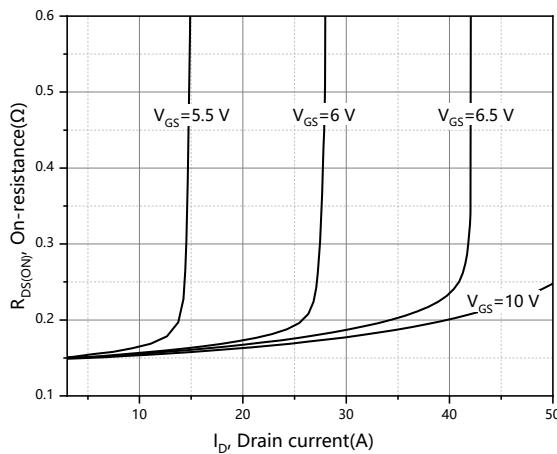
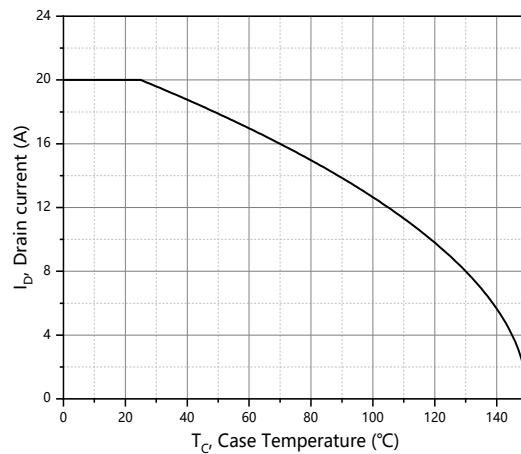
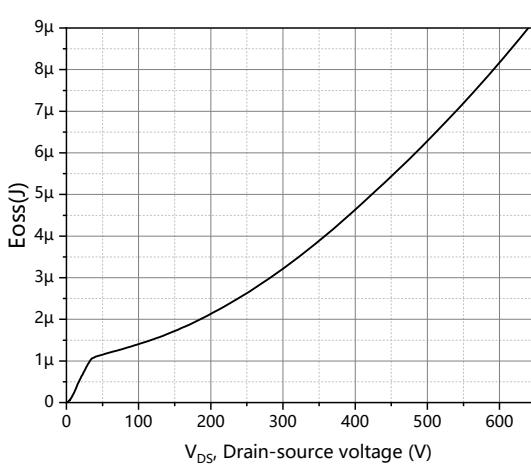
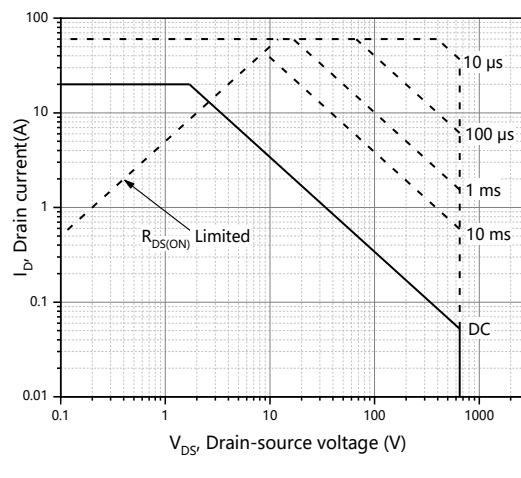
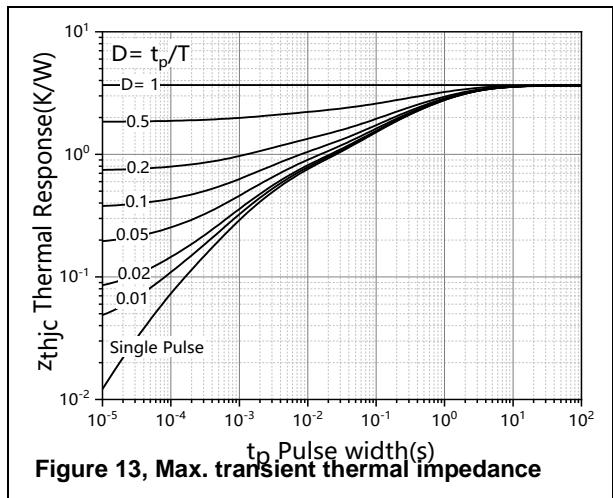


Figure 6. Drain-source on-state resistance


Figure 7. Threshold voltage

Figure 8. Forward characteristic of body diode

Figure 9. Drain-source on-state resistance

Figure 10. Drain current

Figure 11. Safe operation area $T_c=25^\circ C$

Figure 12. Safe operation area $T_c=25^\circ C$



Test circuits and waveforms

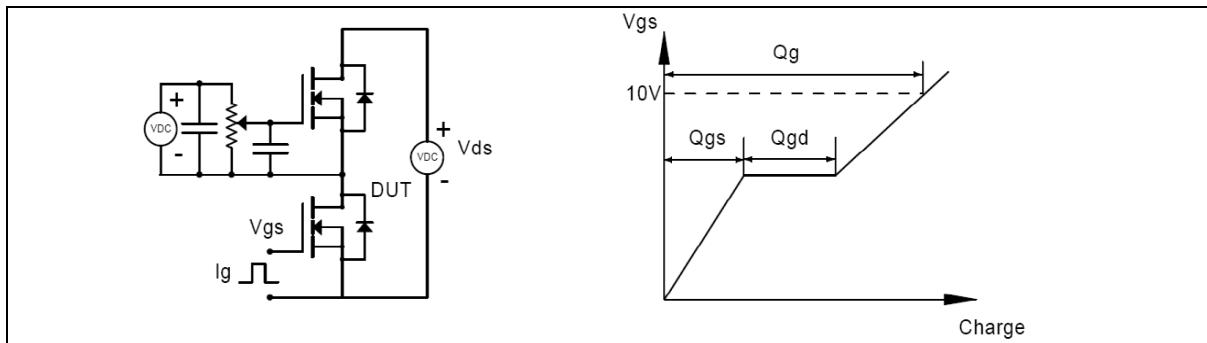


Figure 1. Gate charge test circuit & waveform

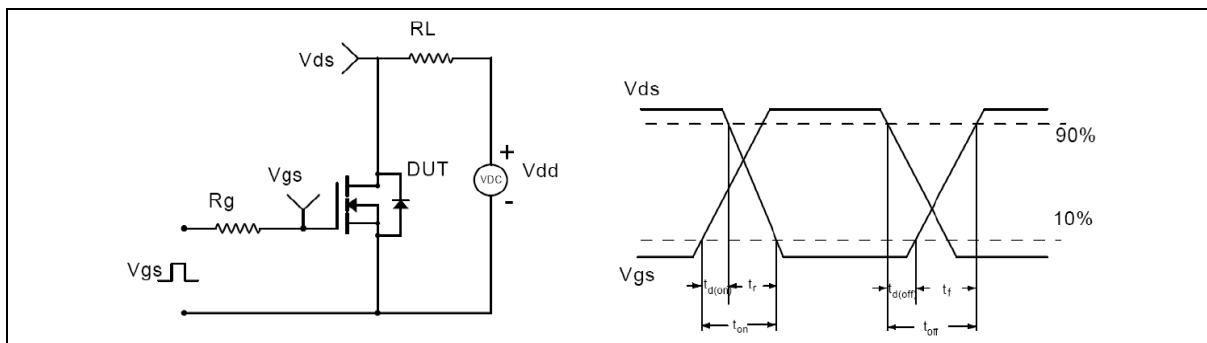


Figure 2. Switching time test circuit & waveforms

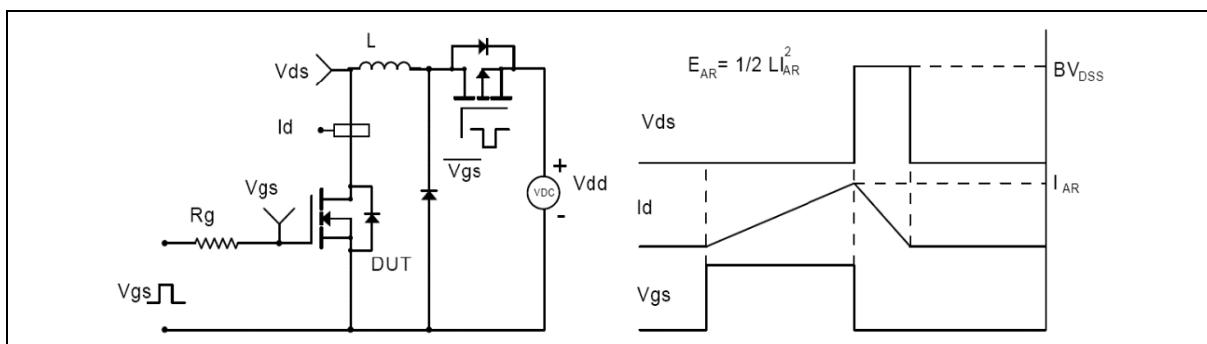


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

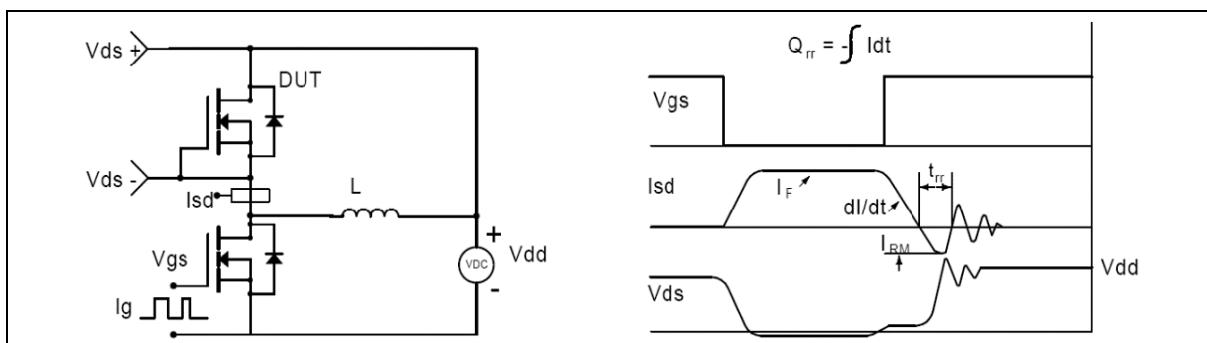
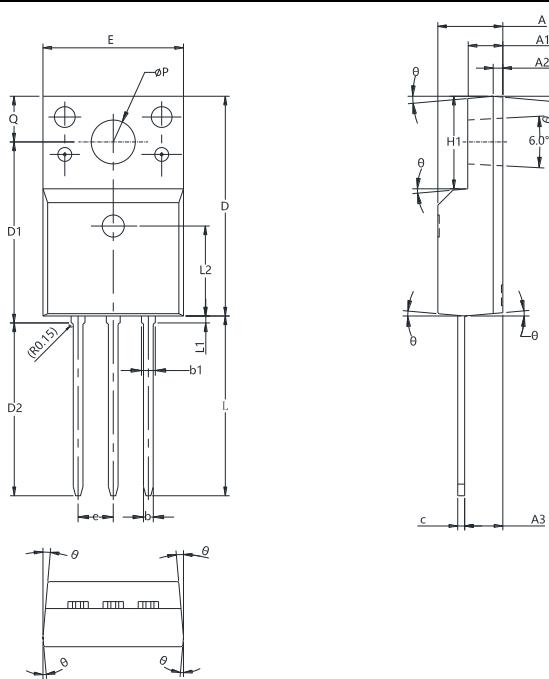


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	4.5	4.7	4.83
A1	2.34	2.54	2.74
A2	0.70 REF		
A3	2.56	2.76	2.93
b	0.6	-	0.8
b1	0.9	-	1.1
c	0.45	0.5	0.6
D	15.67	15.87	16.07
D1	12.87	13.07	13.27
D2	12.28	12.48	12.68
E	9.96	10.16	10.36
e	2.54 BSC		
H1	6.48	6.68	6.88
L	12.68	12.98	13.28
L1	-	-	0.85
L2	6.50 REF		
ΦP	3.08	3.18	3.28
Q	3.20	-	3.40
θ1	1°	3°	5°

Version 1: TO220F_NL-J package outline dimension

Ordering Information

Package Type	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO220F_NL-J	50	20	1000	5	5000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R200FSF_NB	TO220F_NL	yes	yes	yes

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